

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hidekazu Miyairi</td> <td>04/25/2012</td> </tr> <tr> <td>Atsushi Hirose</td> <td>04/26/2012</td> </tr> <tr> <td>Yoshitaka Yamamoto</td> <td>05/15/2012</td> </tr> <tr> <td>Tomohiro Kimura</td> <td>04/26/2012</td> </tr> </tbody> </table>		Name	Execution Date	Hidekazu Miyairi	04/25/2012	Atsushi Hirose	04/26/2012	Yoshitaka Yamamoto	05/15/2012	Tomohiro Kimura	04/26/2012
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<table border="1"> <tr> <td>Name:</td> <td>Semiconductor Energy Laboratory Co., Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>398, Hase</td> </tr> <tr> <td>City:</td> <td>Atsugi-shi, Kanagawa-ken</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>243-0036</td> </tr> </table>		Name:	Semiconductor Energy Laboratory Co., Ltd.	Street Address:	398, Hase	City:	Atsugi-shi, Kanagawa-ken	State/Country:	JAPAN	Postal Code:	243-0036
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PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13477373</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13477373						
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CORRESPONDENCE DATA											
Fax Number:	(703)766-2394										
Phone:	(571) 434-6789										
Email:	uspto@riplo.com										
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>											
Correspondent Name:	Eric J. Robinson										

OP \$40.00 13477373

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Address Line 2: 3975 Fair Ridge Drive, Suite 20 North
Address Line 4: Fairfax, VIRGINIA 22033

ATTORNEY DOCKET NUMBER: 0756-9787

NAME OF SUBMITTER: Eric J. Robinson

Total Attachments: 4
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source=assignment#page4.tif

ASSIGNMENT

Serial No. _____

Filed _____

WHEREAS, Hidekazu MIYAIRI, Atsushi HIROSE, Yoshitaka YAMAMOTO and Tomohiro KIMURA

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in SEMICONDUCTOR DEVICE for which an application for Letters Patent of the United States of America has been executed by the undersigned on _____, and;

WHEREAS, Semiconductor Energy Laboratory Co., Ltd. of 398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan and Sharp Kabushiki Kaisha of 22-22, Nagaike-cho, Abeno-ku, Osaka-shi, Osaka 545-8522 Japan and its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America and its territories and for all foreign countries, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or any continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims under or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and

Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of ROBINSON INTELLECTUAL PROPERTY LAW OFFICE the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

In witness thereof, this Assignment has been executed by the undersigned on the date(s) opposite the undersigned name(s).

Date 04/25/2012 Signature Hidekazu MIYAIRI
Name Hidekazu MIYAIRI

Date 04/26/2012 Signature Atsushi HIROSE
Name Atsushi HIROSE

Date _____ Signature _____
Name Yoshitaka YAMAMOTO

Date _____ Signature _____
Name Tomohiro KIMURA

This assignment should preferably be acknowledged before a United States Consul or Notary Public. If not, then the execution by the Inventor(s) should be witnessed has (have) invented certain new and useful improvements in by at least two other persons who should sign here.

Witness _____ Signature _____

Witness _____ Signature _____

Witness _____ Signature _____

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NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America and its territories and for all foreign countries, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

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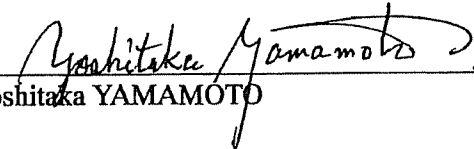
Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

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Date _____ Signature _____
Name Hidekazu MIYAIRI

Date _____ Signature _____
Name Atsushi HIROSE

Date May 15 2012 Signature 
Name Yoshitaka YAMAMOTO

Date April 26, 2012 Signature 
Name Tomohiro KIMURA

This assignment should preferably be acknowledged before a United States Consul or Notary Public. If not, then the execution by the Inventor(s) should be witnessed has (have) invented certain new and useful improvements in by at least two other persons who should sign here.

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